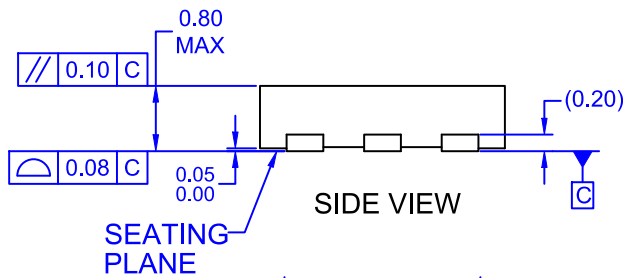
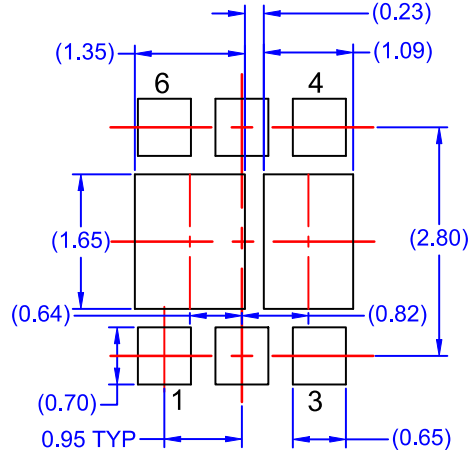
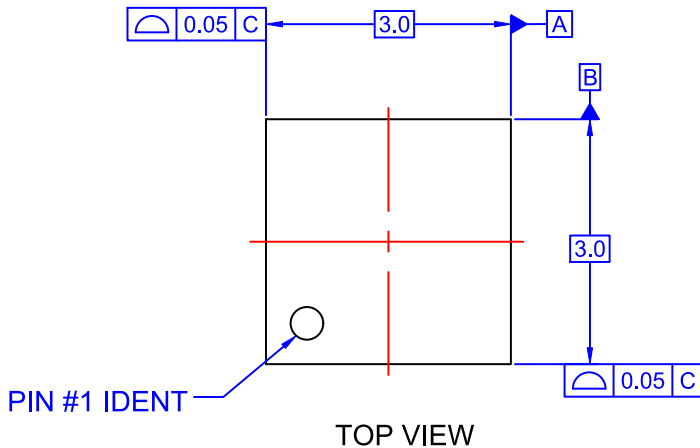




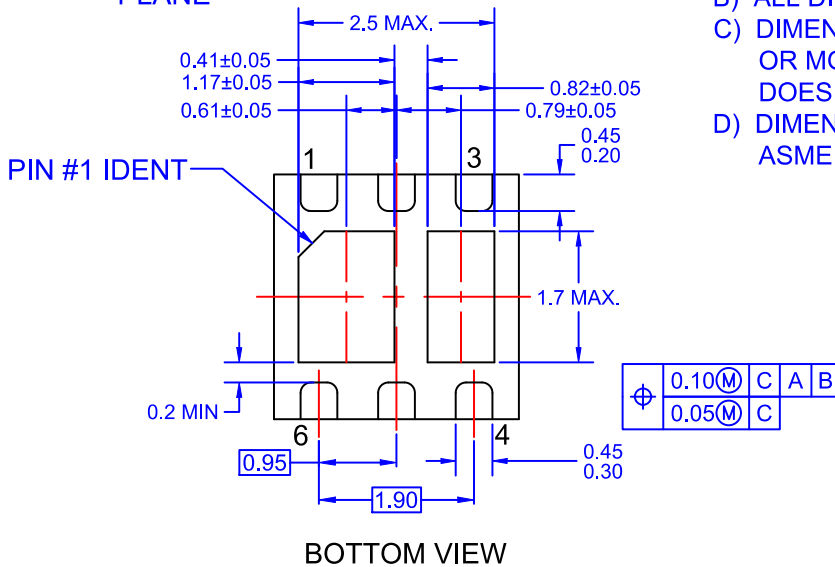
**WDFN6 3x3, 0.95P**  
**CASE 511DT**  
**ISSUE O**

DATE 31 DEC 2016



**RECOMMENDED LAND PATTERN**

- NOTES: UNLESS OTHERWISE SPECIFIED**
- A) CONFORMS TO JEDEC REGISTRATION, MO-229, VARIATION WEEA
  - B) ALL DIMENSIONS ARE IN MILLIMETERS.
  - C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
  - D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.



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<b>DESCRIPTION:</b>	<b>WDFN6 3x3, 0.95P</b>	<b>PAGE 1 OF 1</b>

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